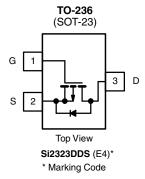




# P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ ) Max.	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)		
- 20	0.039 at V <sub>GS</sub> = - 4.5 V	- 5.3			
	0.050 at V <sub>GS</sub> = - 2.5 V	- 4.7	13.6 nC		
	0.075 at V <sub>GS</sub> = - 1.8 V	- 3.8			



#### **Ordering Information:**

Si2323DDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

### **FEATURES**

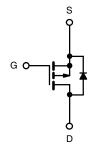
- TrenchFET® Power MOSFET
- 100 % R<sub>a</sub> Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- Load Switch
- PA Switch
- DC/DC Converters
- **Power Management**



P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	- 20	V		
Gate-Source Voltage		$V_{GS}$	± 8	V	
	T <sub>C</sub> = 25 °C		- 5.3	A	
Continuous Dusin Comment (T., 150 °C)	T <sub>C</sub> = 70 °C		- 4.3		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 4.1 <sup>a,b</sup>		
	T <sub>A</sub> = 70 °C		- 3.2 <sup>a,b</sup>		
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	- 20		
Continuous Courses Brain Binds Coursest	T <sub>C</sub> = 25 °C		- 1.4		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 0.8 <sup>a,b</sup>		
	T <sub>C</sub> = 25 °C		1.7		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	<u> </u>	1.1	,,,,	
	T <sub>A</sub> = 25 °C	$P_{D}$	0.96 <sup>a,b</sup>	W	
	T <sub>A</sub> = 70 °C		0.62 <sup>a,b</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 5 s	R <sub>thJA</sub>	100	130	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	60	75	C/VV		

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 175  $^{\circ}\text{C/W}.$
- d.  $T_C = 25$  °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	, , , , , , , , , , , , , , , , , , ,				l		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		- 13		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		- 2.8			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zava Cata Valtaga Dvain Curvant	1	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 15			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.1 A		0.032	0.039	50 Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 2 A		0.041	0.050		
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.058	0.075		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 4.1 A		18		S	
Dynamic <sup>b</sup>	L			I	I	L	
Input Capacitance	C <sub>iss</sub>			1160		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		135			
Reverse Transfer Capacitance	C <sub>rss</sub>			120			
Total Gate Charge	Qg	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 8 V, I <sub>D</sub> = - 4.1 A		24	36		
Total Gate Charge	Qg			13.6	21	nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.1 A		2			
Gate-Drain Charge	Q <sub>gd</sub>			2.2			
Gate Resistance	$R_{g}$	f = 1 MHz	2	10	20	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			24	36		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_L = 3.1 \Omega$		22	40		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 3.2 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		52	78		
Fall Time	t <sub>f</sub>			11	20		
Turn-On Delay Time	t <sub>d(on)</sub>			8	16	ns -	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V}, R_L = 3.1 \Omega$		9	18		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 3.2 A, $V_{GEN}$ = - 8 V, $R_g$ = 1 $\Omega$		58	87		
Fall Time	t <sub>f</sub>			9	18		
<b>Drain-Source Body Diode Characterist</b>	ics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.4	Α	
Pulse Diode Forward Current	I <sub>SM</sub>				- 20	^	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 3.2 A, V <sub>GS</sub> = 0 V		- 0.79	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			14	25	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 3.2 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		6	12	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	1		8		ne	
Reverse Recovery Rise Time	t <sub>b</sub>			6		ns	

#### Notes:

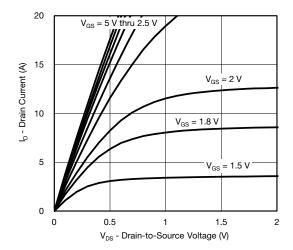
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

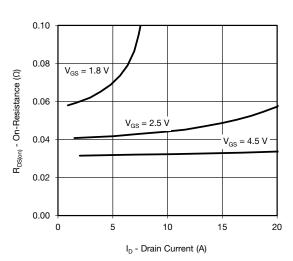
b. Guaranteed by design, not subject to production testing.



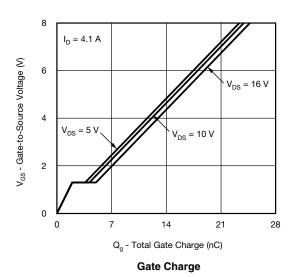
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

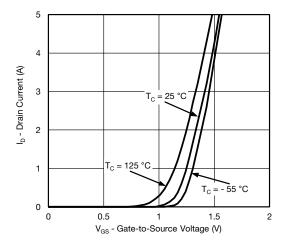


#### **Output Characteristics**

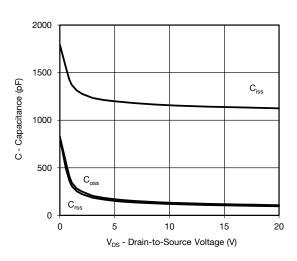


On-Resistance vs. Drain Current and Gate Voltage

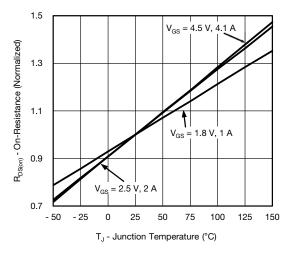




**Transfer Characteristics** 

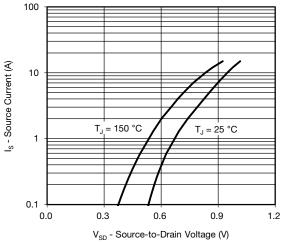


Capacitance

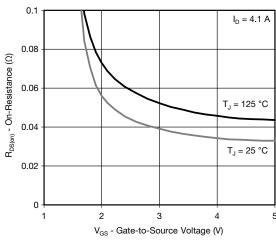


On-Resistance vs. Junction Temperature

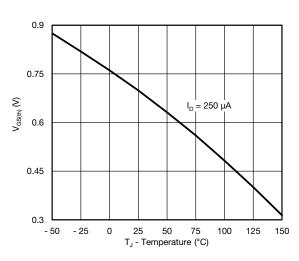
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



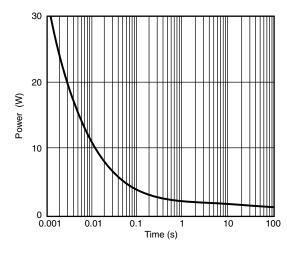
Source-Drain Diode Forward Voltage



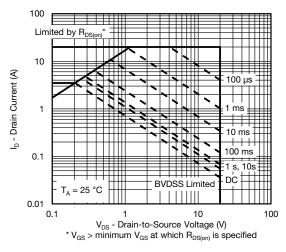
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



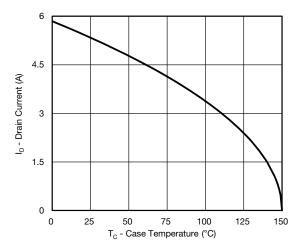
Single Pulse Power, Junction-to-Ambient

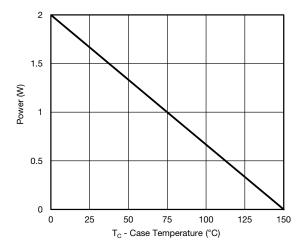


Safe Operating Area, Junction-to-Ambient



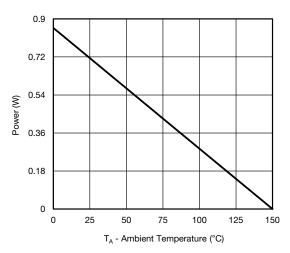
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





**Current Derating\*** 

Power Derating, Junction-to-Foot

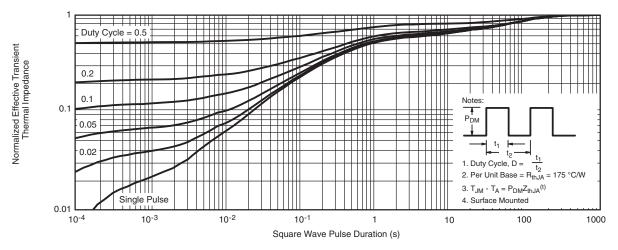


Power, Junction-to-Ambient

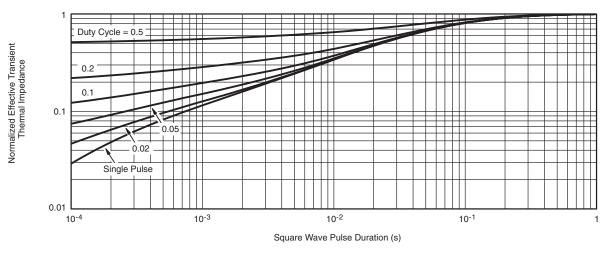
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



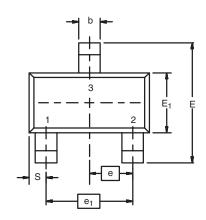
#### Normalized Thermal Transient Impedance, Junction-to-Ambient

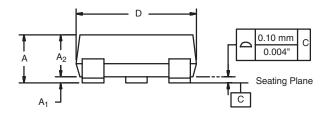


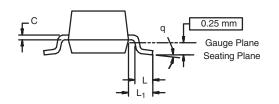
Normalized Thermal Transient Impedance, Junction-to-Foot

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# SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES			
	Min	Max	Min	Max		
Α	0.89	1.12	0.035	0.044		
A <sub>1</sub>	0.01	0.10	0.0004	0.004		
A <sub>2</sub>	0.88	1.02	0.0346	0.040		
b	0.35	0.50	0.014	0.020		
С	0.085	0.18	0.003	0.007		
D	2.80	3.04	0.110	0.120		
E	2.10	2.64	0.083	0.104		
E <sub>1</sub>	1.20	1.40	0.047	0.055		
е	0.9	5 BSC	0.037	4 Ref		
e <sub>1</sub>	1.90 BSC		0.074	'48 Ref		
L	0.40	0.60	0.016	0.024		
L <sub>1</sub>	0.6	0.64 Ref 0.025 Re		5 Ref		
S	0.5	0.50 Ref 0.020 Ref		) Ref		
q	3°	8°	3°	8°		
FCN: S-03946-Rev K 09-	lul-01	•				

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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